

CLAIMS:

1. A dicing/die bonding adhesion tape comprising a substrate, a silicone adhesive layer on the substrate, and a bonding layer on the silicone adhesive layer, wherein  
5 the tack strength between the silicone adhesive layer and the bonding layer is 0.2 to 2.0 N/25 mm, and  
said bonding layer is formed of an bonding composition comprising (A) a polyimide resin, (B) an epoxy resin, and (C)  
10 an epoxy resin curing catalyst.
2. The adhesion tape of claim 1, wherein the substrate is an extensible film.
- 15 3. The adhesion tape of claim 2, wherein the extensible film is polyethylene or polypropylene.
4. The adhesion tape of claim 1, wherein the silicone adhesive comprises a platinum addition-curable or  
20 radiation-curable silicone adhesive material.
5. The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has phenolic hydroxyl radicals on its polymer skeleton.  
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6. The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has a siloxane structure in its polymer skeleton.